

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

**Title of  
Invention**

PARTIAL WAFER BONDING AND DICING

Application Number :

10/710,880

Confirmation Number:

First Named Applicant:

Louis Hsu

Attorney Docket Number:

FIS920040114US1

Art Unit:

Examiner:

Search string:

( 4962879 or 6004866 or 6010591 or 6013534 or 6538330 or 6616854 ).pn

## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

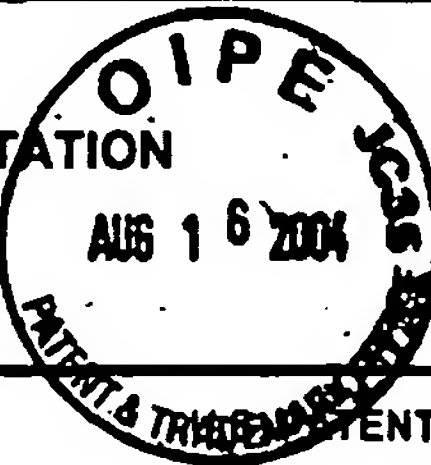
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1A	1	4962879	1990-10-16	Goesele et al	—	—	—
	2	6004866	1999-12-21	Nakano et al	—	—	—
	3	6010591	2000-01-04	Gosele	—	—	—
	4	6013534	2000-01-11	Mountain	—	—	—
	5	6538330	2003-03-25	Forbes	—	—	—
1A	6	6616854	2003-09-09	Jones et al	—	—	—

## Signature

Examiner Name	Date
<i>Agarwal</i>	5/30/05

# INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)



ATTY DOCKET NO.  
FIS920040114US1

APPLICATION NO.  
10/710,880

Hsu et al.

FILING  
Concurrently Herewith

GROUP ART  
Unknown

## PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

## U.S. PATENT APPLICATION PUBLICATIONS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
LA	WO9925019	05/20/99	International				

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

LA		K. Gann, "High Density Packaging of Flash Memory", IEEE, 1998, pp. 96-98.
LA		V. Dragoi et al., "Reversible Wafer Bonding For Reliable Compound Semiconductor Processing", IEEE, 2002, pp. 331-334.

EXAMINER

*[Signature]*

DATE CONSIDERED

5/30/05

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)

1A			G. Reed, "Semiconductor Packaging", Semiconductor International, September, 2003, pp. 50.

EXAMINER

*[Signature]*

DATE CONSIDERED

5/30/05

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